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Siliup Semiconductor

SP60N02BGNK

60V N-Channel Power MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
60V	2.3mΩ@10V	120A
	2.7mΩ@4.5V	

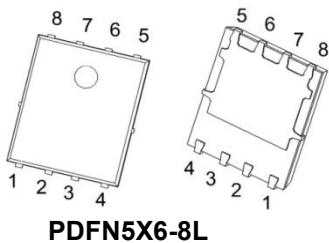
Feature

- Trench Power Technology
- Low RDS(ON)
- Low Gate Charge
- Optimized for Fast-switching Applications

Application

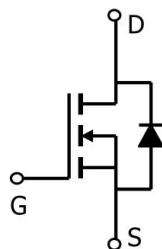
- High Speed Power Switching
- DC/DC Converters

Package

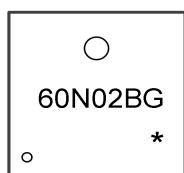


PDFN5X6-8L

Circuit diagram



Marking



60N02BG : Product code

** : Month code.



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Absolute maximum ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	60	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current (T _c =25°C, Silicon limited)	I _D	240	A
Continuous Drain Current (T _c =25°C, Package limited)	I _D	120	A
Pulsed Drain Current	I _{DM}	480	A
Single Pulse Avalanche Energy (note1)	E _{AS}	243	mJ
Power Dissipation (T _c =25°C)	P _D	125	W
Thermal Resistance,Junction-to-Case	R _{θJC}	1	°C/W
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55~+150	°C

Electrical characteristics (T_A=25 °C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, ID = 250μA	60	--	--	V
Zero Gate Voltage Drain Current	I _{DS}	V _{DS} = 48V, V _{GS} = 0V	--	--	1	μA
Gate-Source Leakage	I _{GSS}	V _{GS} = ±20V	--	--	±100	nA
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , ID = 250μA	1.2	1.7	2.2	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, ID = 40A	--	2.3	2.9	mΩ
		V _{GS} = 4.5V, ID = 40A	--	2.7	4.3	
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 30V, f = 1.0MHz	--	3910	--	pF
Output Capacitance	C _{oss}		--	1300	--	
Reverse Transfer Capacitance	C _{rss}		--	11	--	
Total Gate Charge	Q _g	VDD = 30V, ID = 40A, VGS = 10V	--	53	--	nC
Gate-Source Charge	Q _{gs}		--	17	--	
Gate-Drain Charge	Q _{gd}		--	10	--	
Turn-on Delay Time	t _{d(on)}	VDD = 30V, VGS = 10V, ID = 40A, RG = 4Ω	--	15	--	ns
Turn-on Rise Time	t _r		--	34	--	
Turn-off Delay Time	t _{d(off)}		--	33	--	
Turn-off Fall Time	t _f		--	9	--	
Drain-Source Body Diode Characteristics						
Body Diode Voltage	V _{SD}	V _{GS} = 0V, IS = 40A,	--	--	1.2	V
Reverse Recovery Time	t _{rr}	IF = 40A, dI/dt = 100A/μs	--	48	--	ns
Reverse Recovery Charge	Q _{rr}		--	99	--	nC

Notes :

1. EAS condition: VDD = 30V, VG=10V,L=0.3mH,Rg=25Ω, TJ = 25°C.

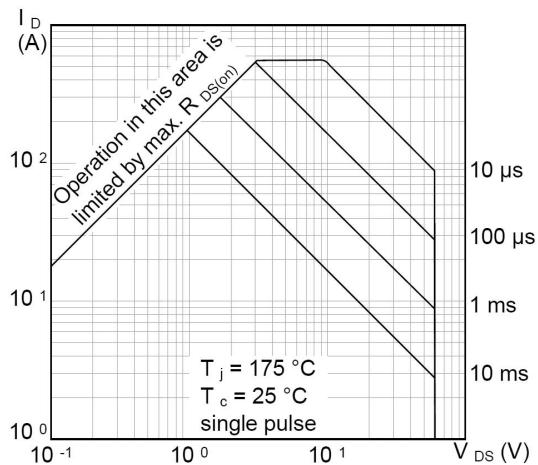


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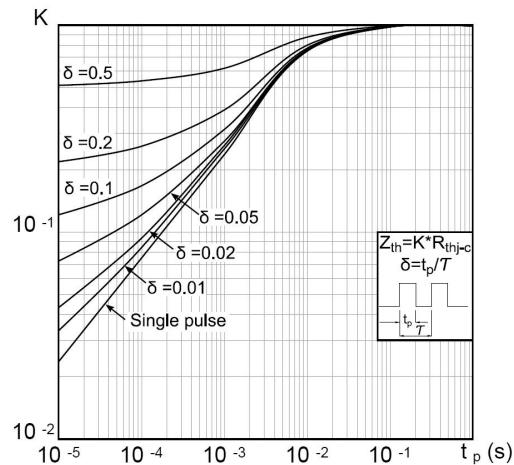
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Typical Characteristics

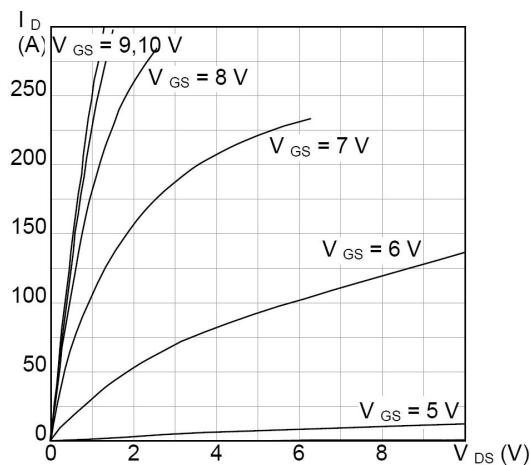
Safe operating area



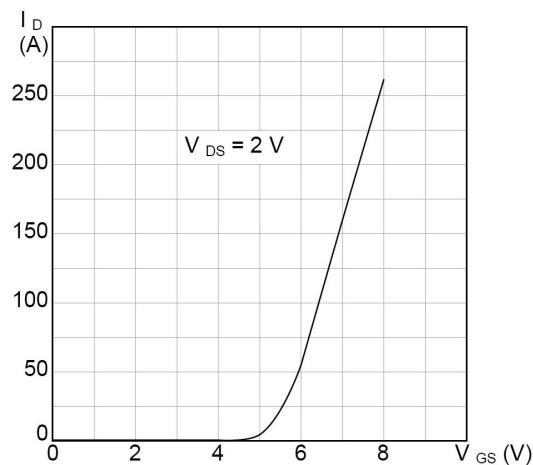
Thermal impedance



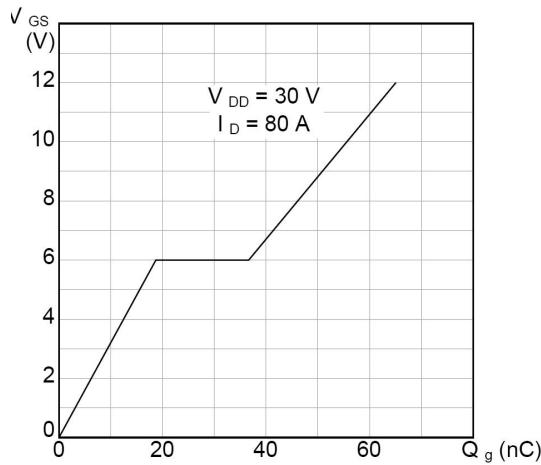
Output characteristics



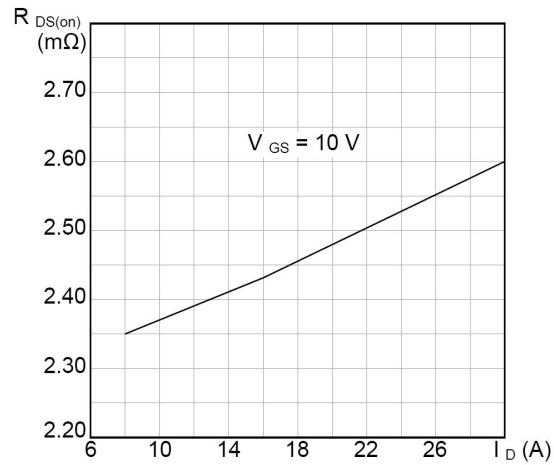
Transfer characteristics



Gate charge vs gate-source voltage



Static drain-source on-resistance





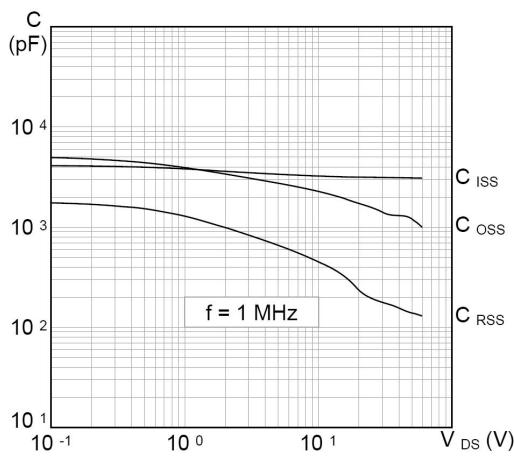
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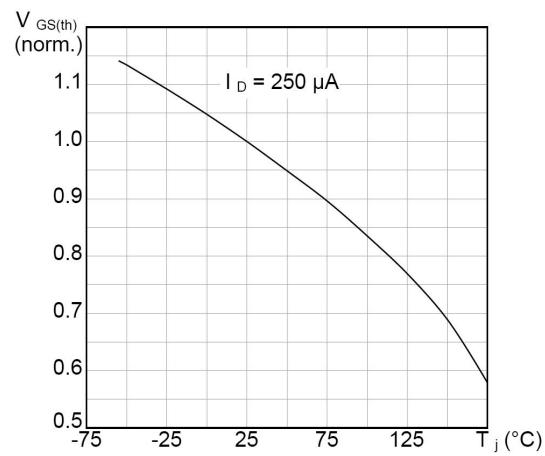
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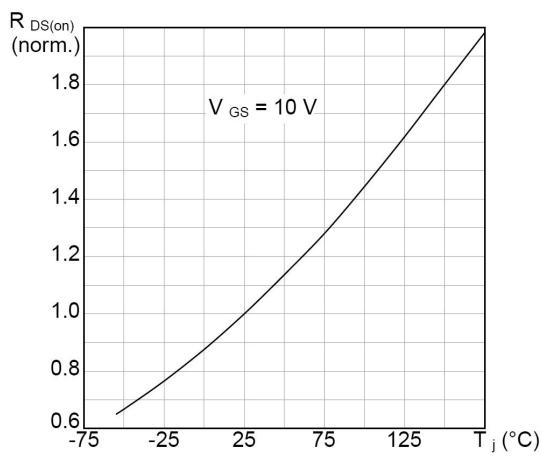
Capacitance variations



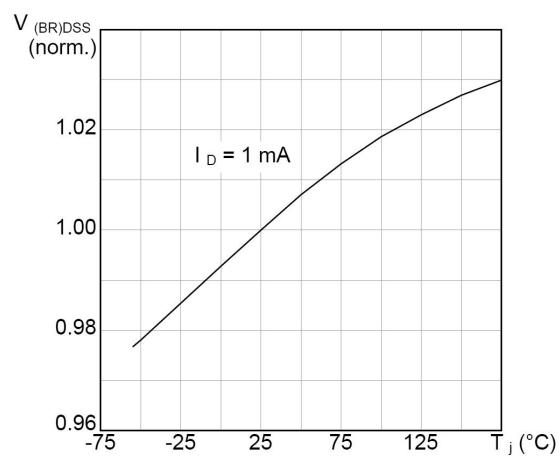
Normalized gate threshold voltage vs temperature



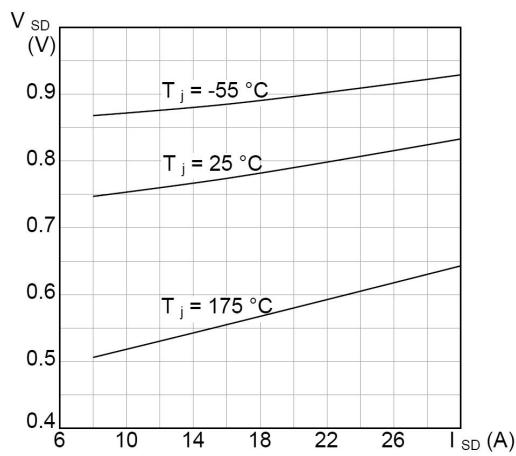
Normalized on-resistance vs temperature



Normalized $V_{(BR)DSS}$ vs temperature



Source-drain diode forward characteristics





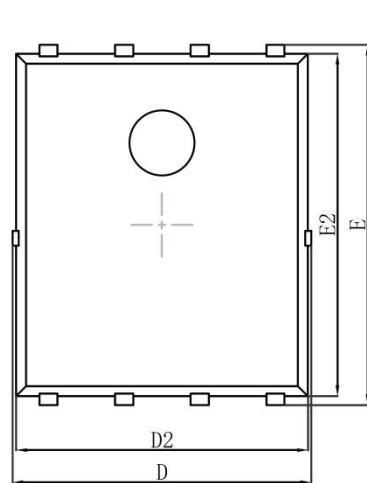
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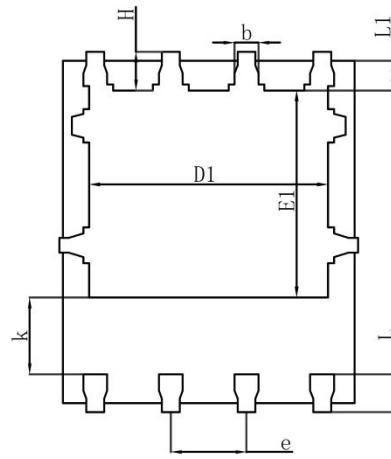
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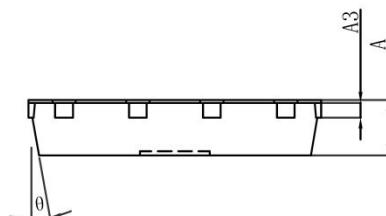
PDFN5X6-8L Package Outline Dimensions



Top View
[顶视图]



Bottom View
[背视图]



Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.			0.010REF.
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°